

	Type	L #	Hits	S arch T xt	DBs	Tim Stamp
1	BRS	L6	2490	semiconductor and (electrolyte and (titanium adj sulfate or titanium adj bromide or titanium adj trichloride or titanium adj idoide or titanium adj fluoride or copper sulfate) and anode)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 16:03
2	BRS	L7	409	6 and (seed adj layer)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 11:39
3	BRS	L8	266	7 and (barrier adj layer)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 11:39
4	BRS	L10	98294	(cvd or (chemical adj vapor adj deposition) or (pecvd or (plasma adj enhanced adj chemical adj vapor adj deposition))) and (dielectric or oxide)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 11:42
5	BRS	L11	195	8 and 10	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 17:16

	Type	L #	Hits	S arch Text	DBs	Tim Stamp
6	BRS	L13	76	11 and (@ad<20010419)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 15:28
7	BRS	L14	71802	reduc\$6 near4 oxide	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 15:29
8	BRS	L15	255	6 and 14	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 15:29
9	BRS	L16	12	15 and 13	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 16:01
10	BRS	L17	467	(reduce or reducing or reduced) near2 oxide near8 (tungsten or W or (tungsten adj nitride) or (tungsten adj silicon adj nitride) or Wn or WsiN)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 16:02

	Typ	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L18	929189	titanium adj sulfate or titanium adj bromide or titanium adj trichloride or titanium adj idoide or titanium adj fluoride or copper sulfate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 16:03
12	BRS	L19	37	17 same 18	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 16:03
13	BRS	L20	3	19 and electrolyte	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 16:04
14	BRS	L21	34	19 not 20	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 16:05
15	BRS	L22	119	11 not 13	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/05/12 17:16